

ABSTRACT

A tested semiconductor device can have scrub marks produced by a process that can include providing a wafer having semiconductor devices thereon and adjusting a planar orientation of probe elements of a probe card assembly to correspond to the orientation of contact terminals on the wafer. The process can also include effecting contact between the probe elements of the probe card assembly and the contact terminals. The contact can cause the probe elements to press against the terminals with a contact force that causes the probes to wipe across the contact terminals, thereby making scrub marks on the contact terminals. The process can also include testing the semiconductor devices.